

Migrate from AIROC™ CYBLE-022001-00 (128 KB flash) with AIROC™ CYBLE-222014-01 (256 KB flash)

About this document

Scope and purpose

This document describes how Infineon's AIROC™ CYBLE-222014-01 Bluetooth® LE module (256 KB flash memory) can replace the AIROC™ CYBLE022001-00 (128 KB flash) without a cost increase. This document provides information on how to migrate from the AIROC™ CYBLE-022001-00 module to AIROC™ CYBLE-222014-01 module in your designs.

Intended audience

The intended audiences for this document are design engineers, technicians, and developers of the AIROC™ CYBLE-022001-00 Bluetooth® LE embedded module.

Migrate from AIROC™ CYBLE-022001-00 (128 KB flash) with AIROC™ CYBLE-222014-01 (256 KB flash)

Table of contents

Table of contents

About this document.....	1
Table of contents.....	2
1 Introduction	3
2 Check the host PCB board	4
2.1 Check PAD6: VREF of the PCB board.....	5
3 Update your application	6
References.....	8
Revision history.....	9
Disclaimer.....	10

Introduction

1 Introduction

Infineon's AIROC™ CYBLE-222014-01 provides 256 KB flash memory which is higher than the 128 KB flash available in AIROC™ CYBLE022001-00 without additional costs. This document provides guidance on migration from AIROC™ CYBLE-022001-00 module to AIROC™ CYBLE-222014-01 module.

Document structure

This document provides the following information.

- **Checking host PCB board:** The pinout differences between AIROC™ CYBLE-022001-00 and AIROC™ CYBLE-222014-01.
- **Updating the customer application:** The procedure and checks to change the device of your application from AIROC™ CYBLE-022001-00 to AIROC™ CYBLE-222014-01.

Check the host PCB board

2 Check the host PCB board

The following figures provide the mechanical drawings with the pad assignments and the dimensions of the CYBLE-022001-00 and CYBLE-222014-01 modules.

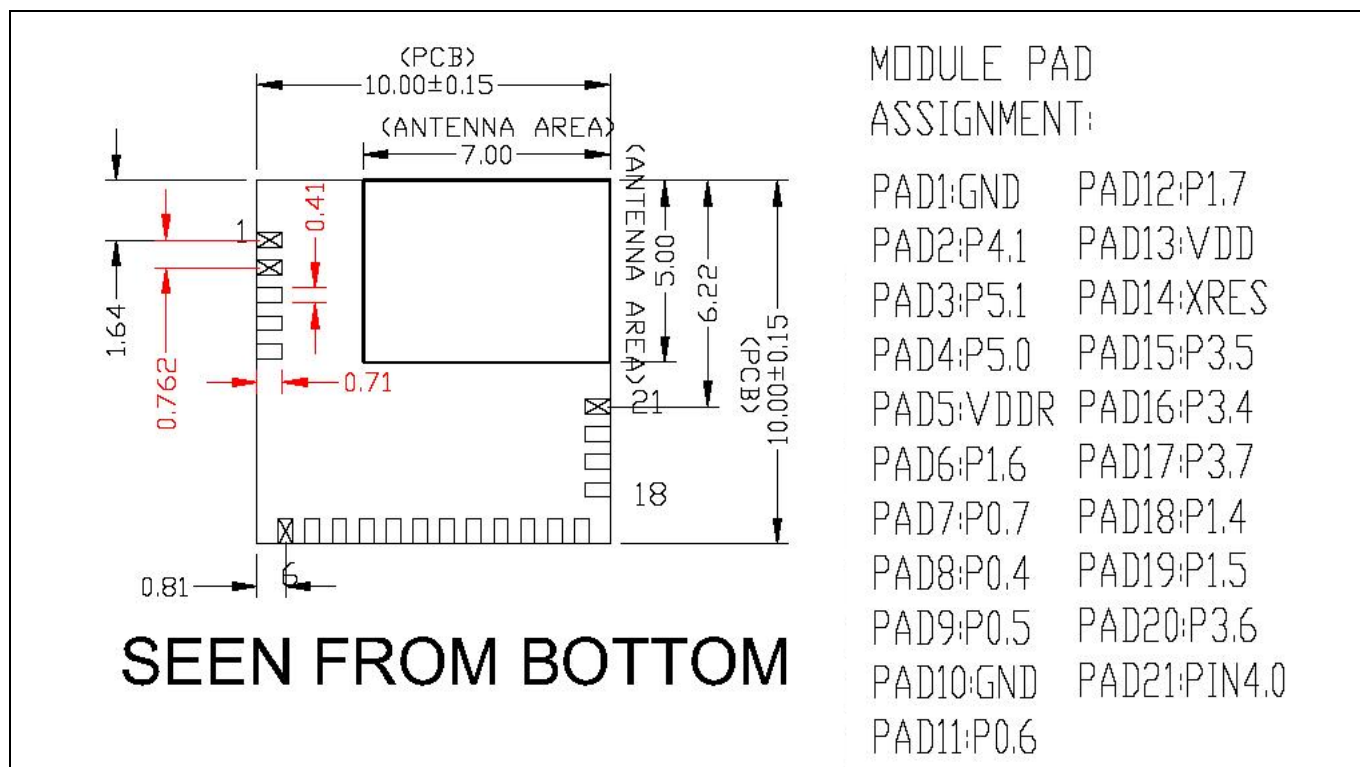


Figure 1 CYBLE-022001-00 pinout and pad assignment

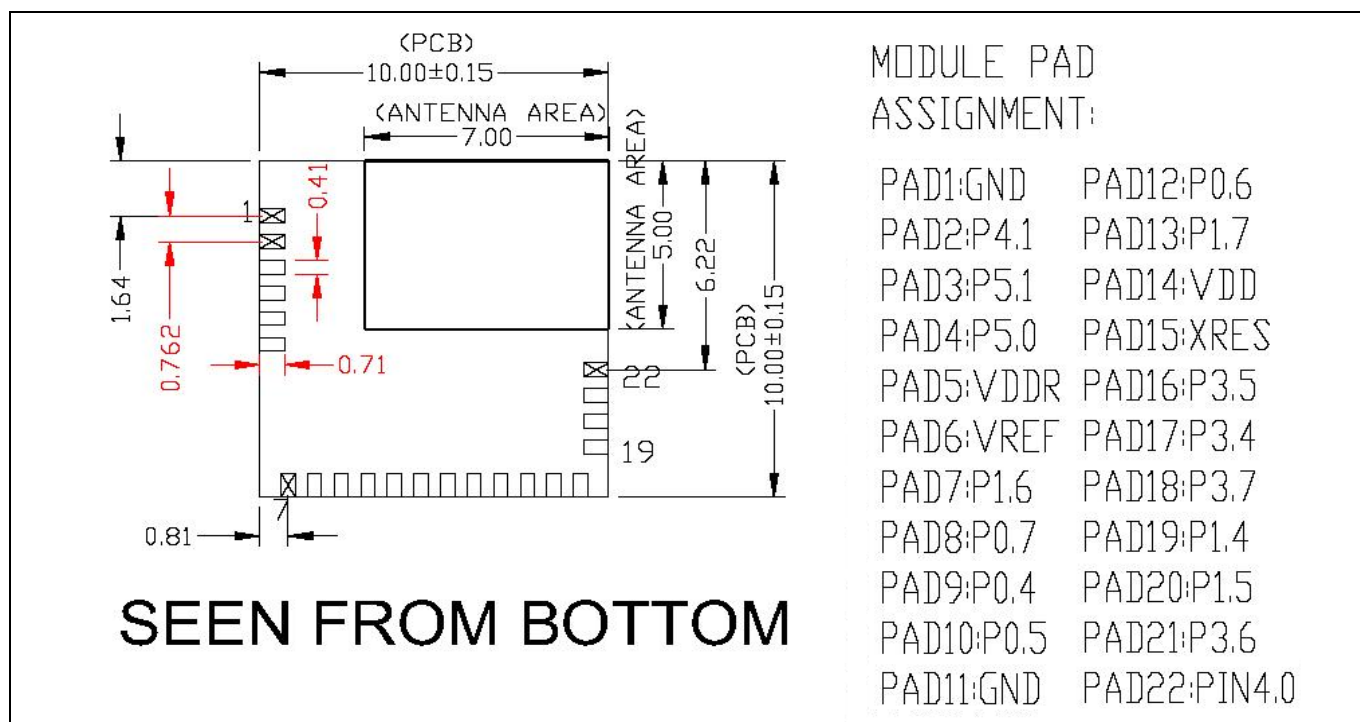


Figure 2 CYBLE-222014-10 pinout and pad assignment

Migrate from AIROC™ CYBLE-022001-00 (128 KB flash) with AIROC™ CYBLE-222014-01 (256 KB flash)

Check the host PCB board

2.1 Check PAD6: VREF of the PCB board

Check the host PCB to make sure PAD6: VREF of CYBLE-222014-01 is floating. If PAD6: VREF of CYBLE 222014-01 is floating, CYBLE-222014-01 can be used as a drop-in compatible part for CYBLE 022001 00.

The following figure shows the pin to be checked.

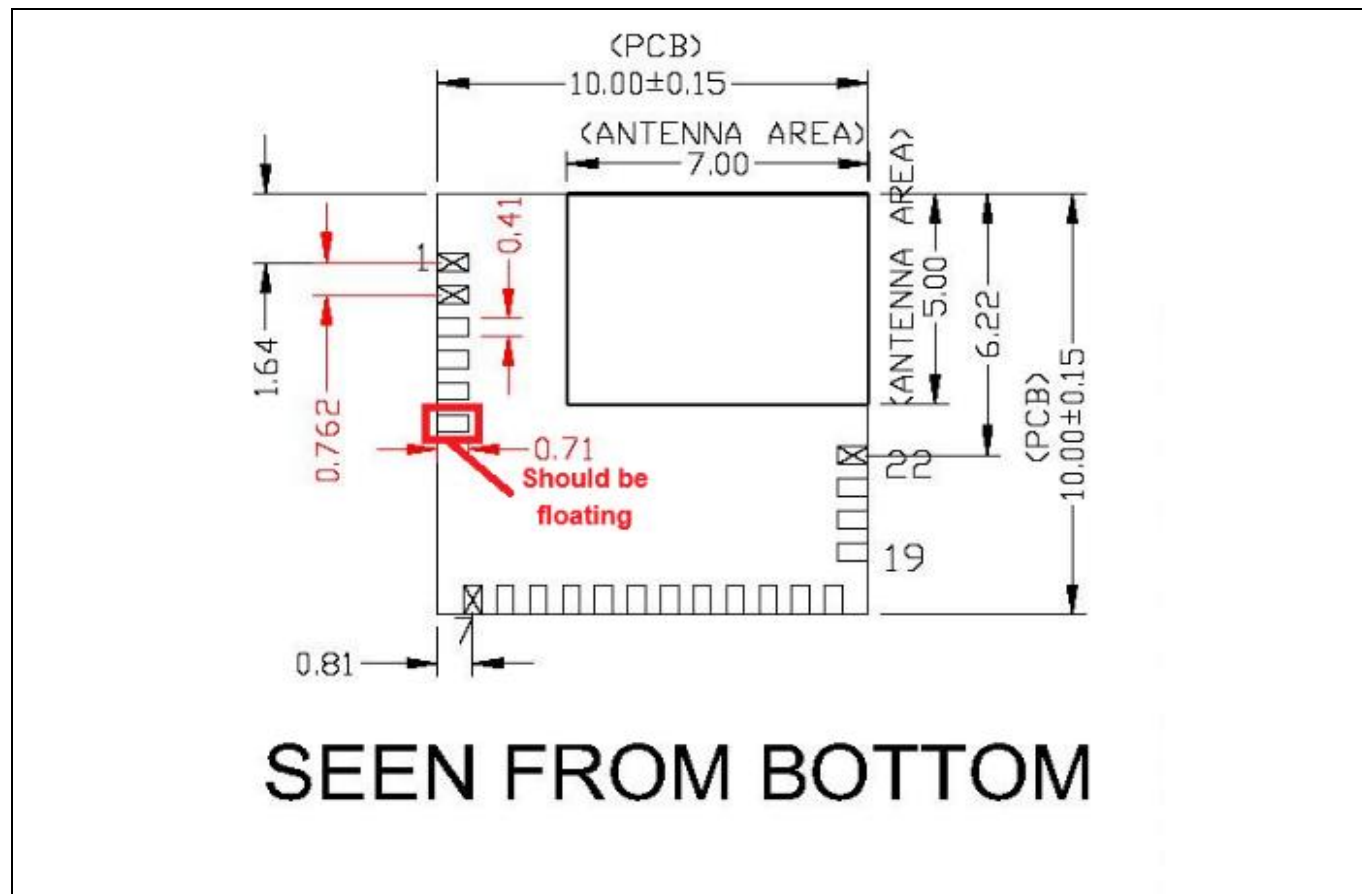


Figure 3 PAD to be checked

Migrate from AIROC™ CYBLE-022001-00 (128 KB flash) with AIROC™ CYBLE-222014-01 (256 KB flash)

Update your application

3 Update your application

The application for your device can be easily updated from CYBLE-022001-00 to CYBLE-222014-01 using the [PSOC™ Creator](#) software.

1. Open your application in PSOC™ Creator.

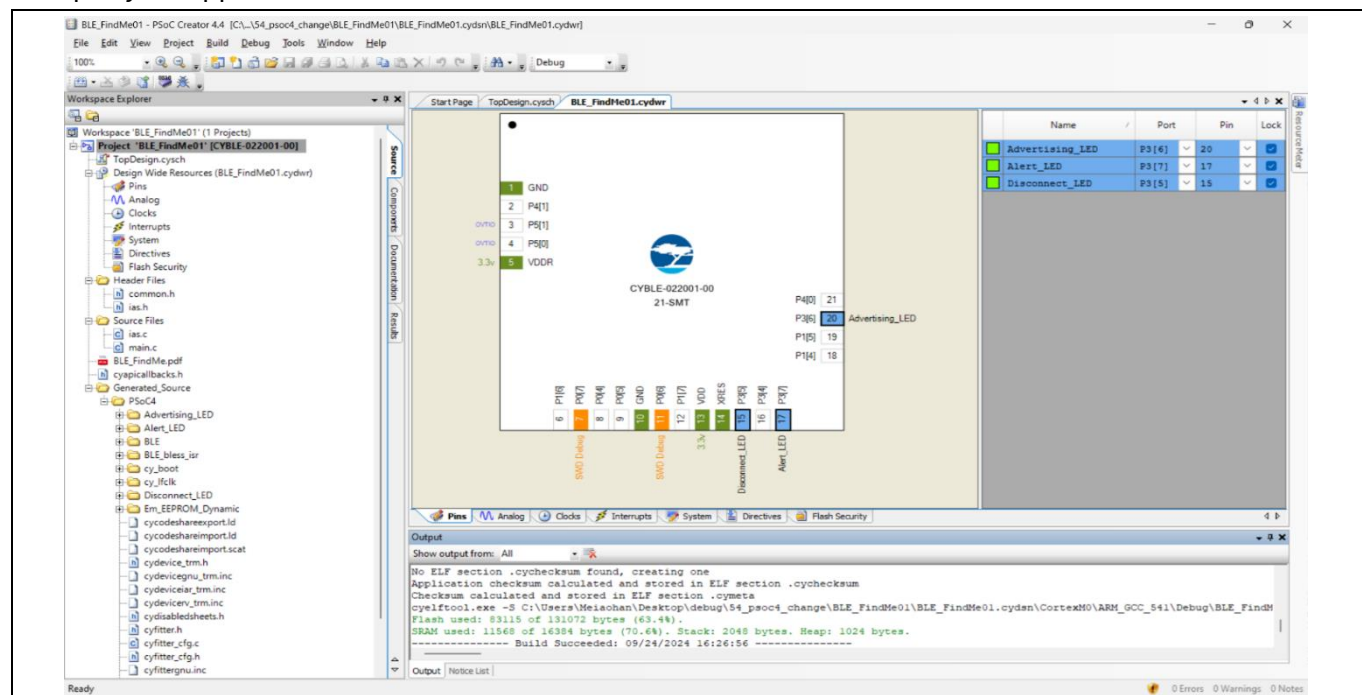


Figure 4 Open customer application in PSOC Creator Software

2. Right-click on the project and select Device Selector.

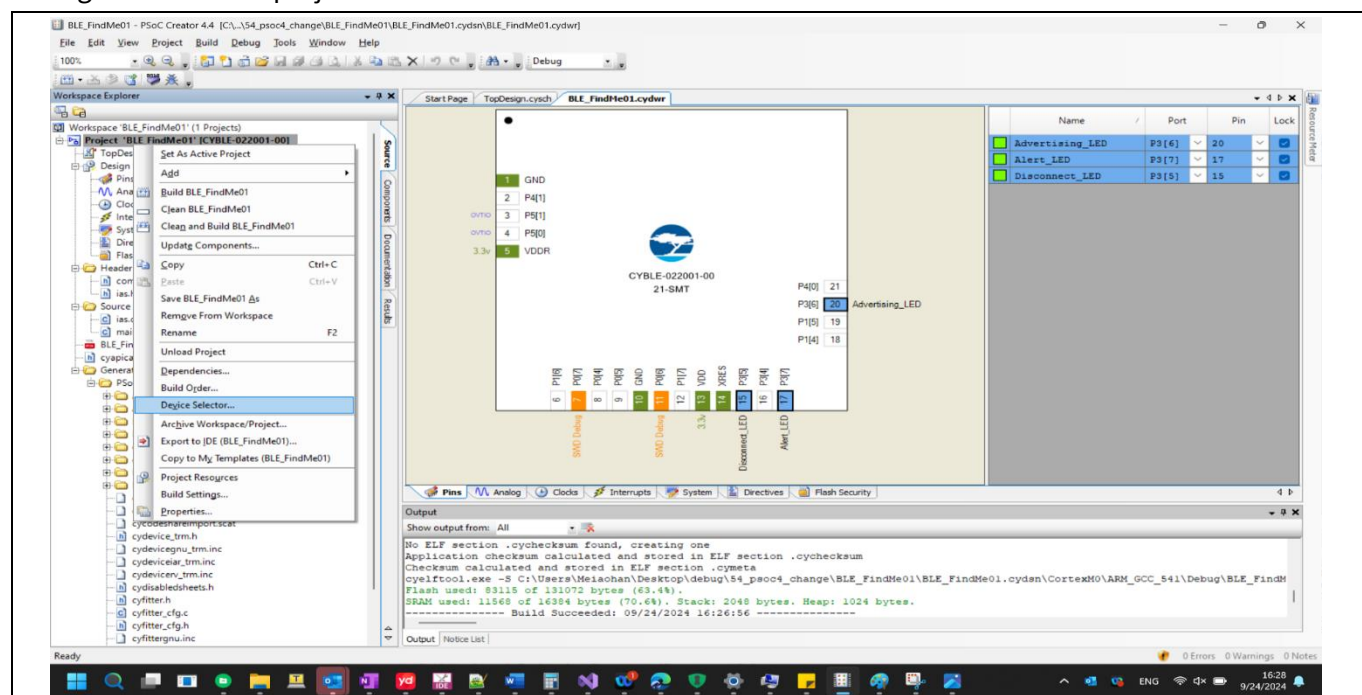


Figure 5 Select Device Selector

Migrate from AIROC™ CYBLE-022001-00 (128 KB flash) with AIROC™ CYBLE-222014-01 (256 KB flash)

Update your application

3. In the Device Selector, select CYBLE-222014-01.

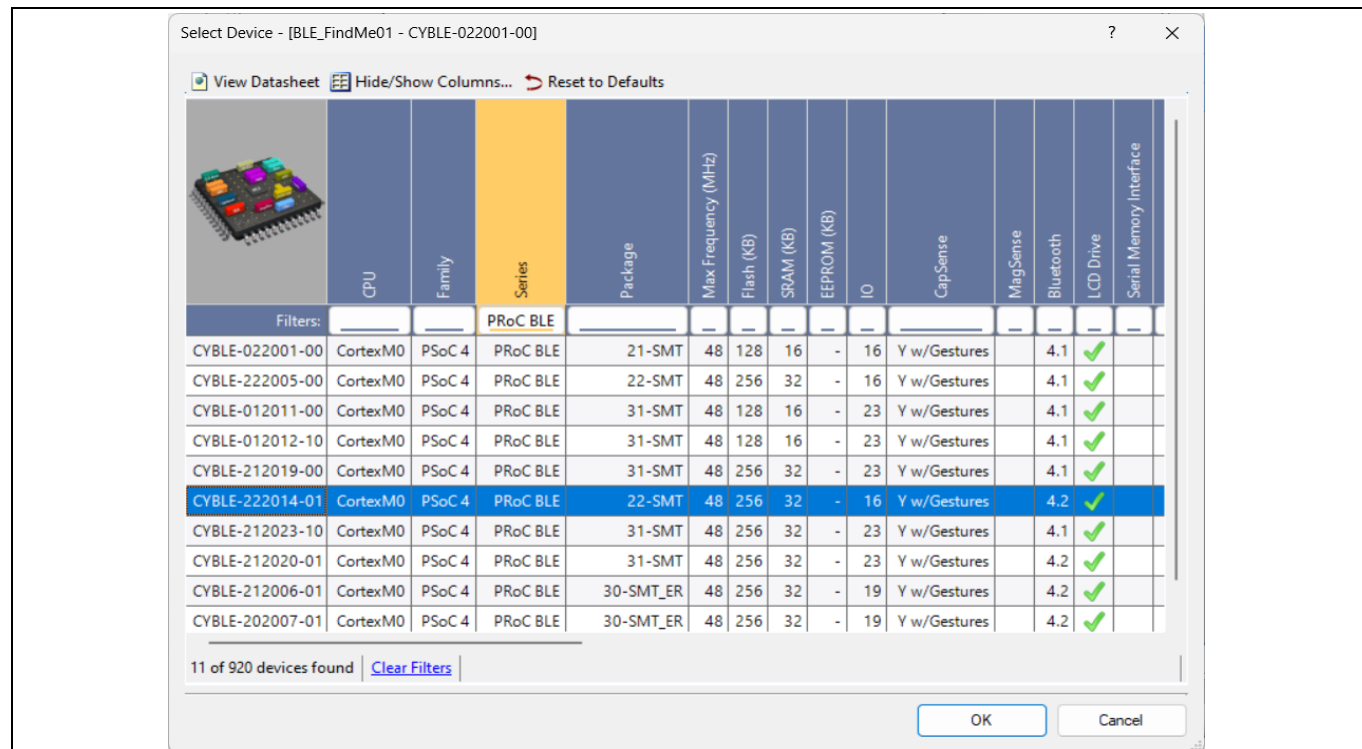


Figure 6 Select CYBLE-222014-01 in Device Selector

The CYBLE-222014-01 is shown in the Workspace Explorer window.

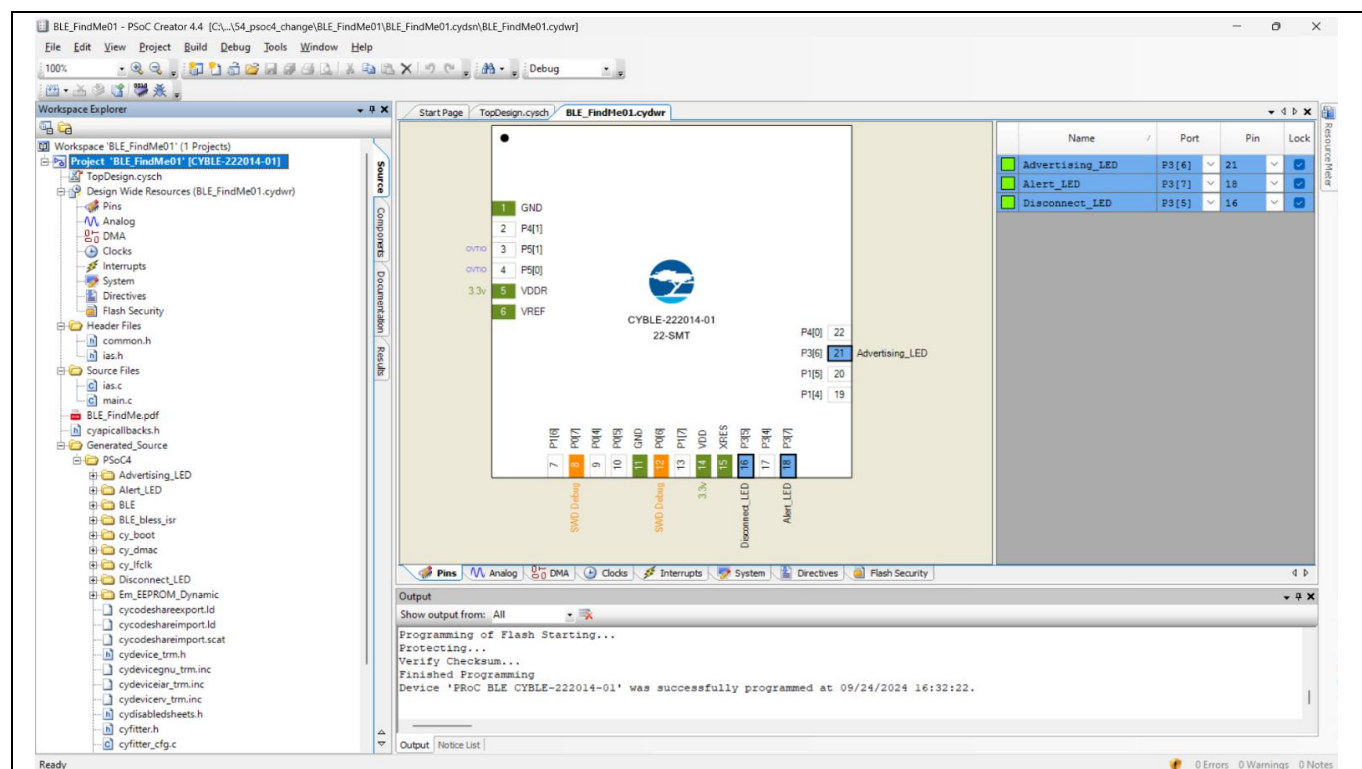


Figure 7 CYBLE-222014-01 is shown in the Workspace Explorer window

Migrate from AIROC™ CYBLE-022001-00 (128 KB flash) with AIROC™ CYBLE-222014-01 (256 KB flash)



References

References

- [1] Infineon Technologies AG: *AIROC™ CYBLE-022001-00 Bluetooth® LE module*; [Available online](#)
- [2] Infineon Technologies AG: *EZ-BLE™ Creator Module, CYBLE-222014-01*; [Available online](#)

Migrate from AIROC™ CYBLE-022001-00 (128 KB flash) with AIROC™ CYBLE-222014-01 (256 KB flash)

Revision history

Revision history

Document revision	Date	Description of changes
**	2024-11-11	Initial release
*A	2025-02-12	Minor updates

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

The Bluetooth® word mark and logos are registered trademarks owned by Bluetooth SIG, Inc., and any use of such marks by Infineon is under license.

Edition 2025-02-12

Published by

Infineon Technologies AG

81726 Munich, Germany

**© 2025 Infineon Technologies AG.
All Rights Reserved.**

Do you have a question about this document?

Email: erratum@infineon.com

Document reference

002-40728 Rev. *A

Important notice

The information contained in this application note is given as a hint for the implementation of the product only and shall in no event be regarded as a description or warranty of a certain functionality, condition or quality of the product. Before implementation of the product, the recipient of this application note must verify any function and other technical information given herein in the real application. Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind (including without limitation warranties of non-infringement of intellectual property rights of any third party) with respect to any and all information given in this application note.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

Warnings

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.